

Docket No.: 2336-247

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of	:	
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Joo Ho LEE <i>et al.</i>	:	<i>Confirmation No. 2626</i>
	:	
U.S. Patent Application No. 10/790,723	:	Group Art Unit: 2826
	:	
Filed: March 3, 2004	:	Examiner: Fetsum Abraham
For:		
WAFER LEVEL PACKAGE FOR MICRO DEVICE AND MANUFACTURING		
METHOD THEREOF		

AMENDMENT

COMMISSIONER FOR PATENTS
P.O. Box 1450
Alexandria VA 22313-1450

Sir:

The following amendments and remarks are submitted in response to the Official Action dated *March 27, 2006*.